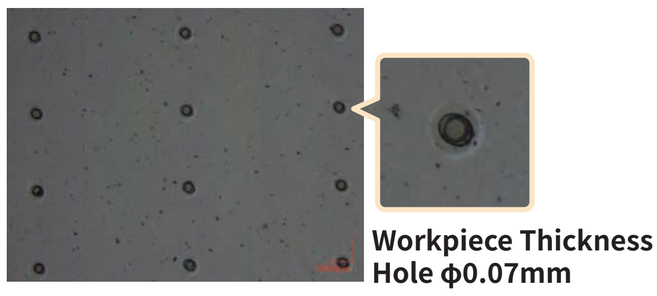
Proposal for Filling Printing for Ceramic Substrates and Wafers

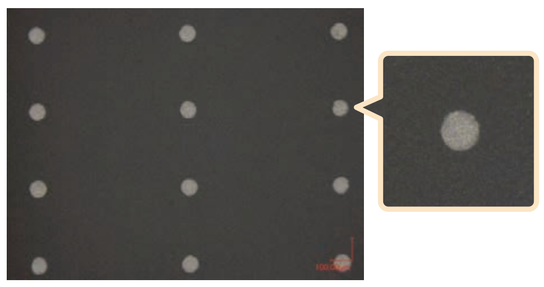
Hole Filling Printing

Hole Filling Printing in Green Sheet (Processing using metal and mesh masks)

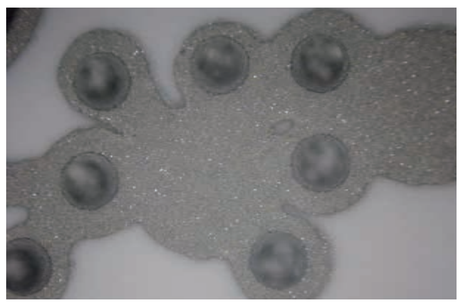


Workpiece Thickness
Hole ϕ0.07mm

Filling

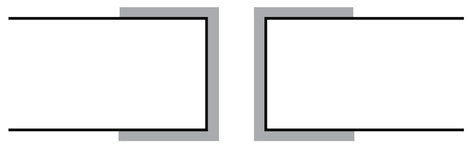


Through-hole processing on green sheets is also available

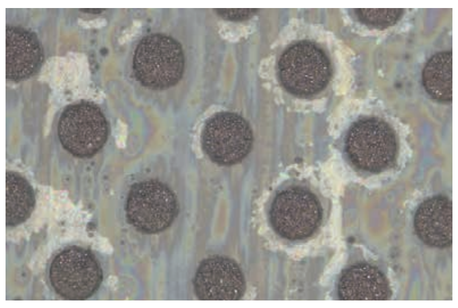


Hole Cross Section

Apply paste to the inner wall of the through-hole



Masking is applied to the substrate, and direct hole filling without a mask



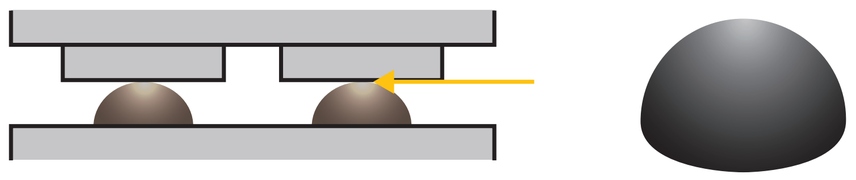
Front: Laminate + Holes

Back: Laminate only (with Bottom)

Groove Filling Printing Forming dielectric pillars on wafers and ceramic substrates

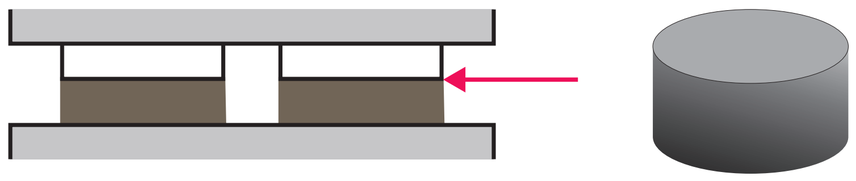
Usually formed by printing or dispenser

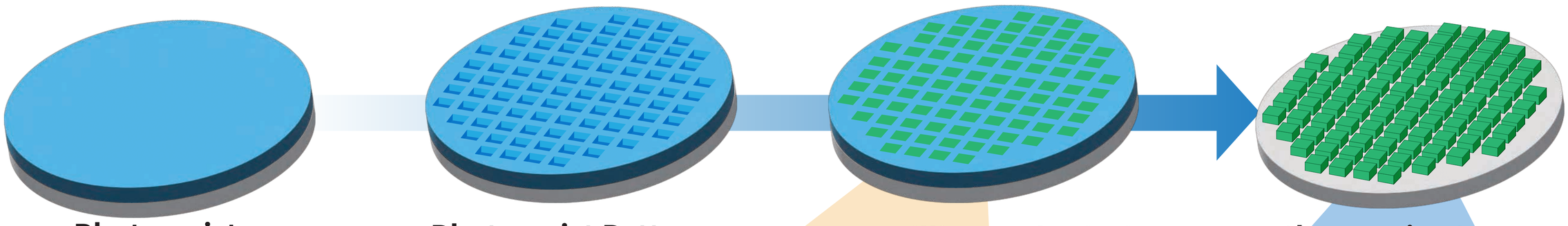
The device becomes unstable because it becomes "Semi-Cylindrical" and there are fewer contact points with the parts



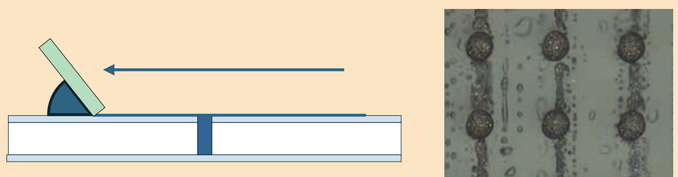
Groove filling formation using photoresist and vacuum printing

Since it can be formed into a "Cylindrical Shape," the contact with the part is wide and stable.

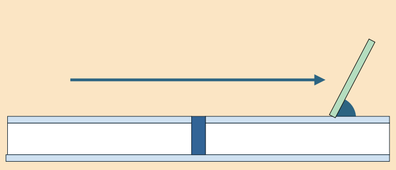




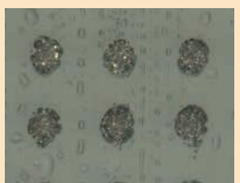
Photoresist → Photoresist Pattern → Paste Filling and Printing → Photoresist Pattern

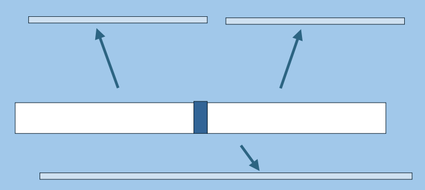


Filling



Scraping





After drying, remove the laminate

SERIA Group Strengths

SERIA
PE Technology Center

Providing a test environment for customers

- Business negotiations, observations, and various tests
- Printing system operation training
- Verification of printing issues and new technologies